



Title of Change:	Datasheet change for LC898123F40XC-VH		
Effective date:	4 April 2017		
Contact information:	Contact your local ON Semiconductor Sales Office or < quality@onsemi.com>		
Type of notification:	ON Semiconductor will consider this change accepted.		
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other: <u>Datasheet</u>		
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change	<input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change	<input checked="" type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable	<input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Leshan, China	<input type="checkbox"/> External Foundry/Subcon site(s)
Description and Purpose:			
This Product Bulletin is being issued to announce an update to the Datasheet of LC898123F40XC-VH (WLCSP35), specifically to add in the BACKSIDE COATING and minimum dimension of the total thickness in the Package dimensions portion. The change will not impact form, fit, or function of product(s)			
List of affected Standard Parts:			
LC898123F40XC-VH			